

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Original) A function module comprising:
 - a first circuit board including a first surface, with a first ground layer formed thereon;
 - a second circuit board, coupled to the first circuit board, including a second surface facing the first surface, wherein a second ground layer is formed on the second surface;
 - and
 - a plate-type heat dissipation device, disposed between the first circuit board and the second circuit board, abutting the first ground layer and the second ground layer respectively.
2. (Original) The function module as claimed in claim 1, wherein the first circuit board further includes a third surface, opposite to the first surface, with a first device located thereon.
3. (Original) The function module as claimed in claim 1, wherein the second circuit board further includes a fourth surface, opposite to the second surface, with a second device located thereon.

4. (Original) The function module as claimed in claim 1, wherein the first ground layer comprises a copper layer.

5. (Original) The function module as claimed in claim 1, wherein the second ground layer comprises a copper layer.

6. (Original) The function module as claimed in claim 1, further comprising a flat cable connecting the first circuit board and the second circuit board, providing communicability therebetween.

7. (Original) The function module as claimed in claim 1, wherein the first circuit board includes a first connector, the second circuit board includes a second connector corresponding to the first connector, and the first circuit board and the second circuit board communicate with each other by the respective connectors.

8. (Original) The function module as claimed in claim 7, wherein the first connector is located on the first surface, and the second connector is located on the second surface.

9. (Original) The function module as claimed in claim 1, further comprising a slot connector connecting the first circuit board and the second circuit board, providing communicability therebetween.

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10. (Original) The function module as claimed in claim 1, wherein the plate-type heat dissipation device is a plate-type heat pipe, a copper plate, a plate-type copper block, a micro fin, a water-cooling device, or a vapor chamber.
11. (Original) The function module as claimed in claim 1, further comprising a heat dissipation fin, connected to the plate-type heat dissipation device, for further dissipation of heat therefrom.
12. (Original) The function module as claimed in claim 11, further comprising a fan, connected to the heat dissipation fin, for further dissipation of heat therefrom.
13. (Original) The function module as claimed in claim 1, further comprising:
a first adhesion layer, disposed between the plate-type heat dissipation device and the first ground layer, for combining the plate-type heat dissipation device with the first circuit board; and
a second adhesion layer, disposed between the plate-type heat dissipation device and the second ground layer, for combining the plate-type heat dissipation device with the second circuit board.
14. (Original) The function module as claimed in claim 13, wherein both the first adhesion layer and the second adhesion layer comprise one selected from the group consisting of brazing solder, tin solder, thermal interface material, grease and the combination thereof respectively.

15. (Original) A function module comprising:
- a first circuit board including a first surface with a first heat conduction layer formed thereon;
 - a second circuit board, coupled to the first circuit board, including a second surface facing the first surface, on which a second heat conduction layer is formed; and
 - a plate-type heat dissipation device, disposed between the first circuit board and the second circuit board, abutting the first heat conduction layer and the second heat conduction layer respectively.
16. (Original) The function module as claimed in claim 15, wherein the first heat conduction layer is a ground layer of the first circuit board, and the second heat conduction layer is a ground layer of the second circuit board.
17. (Original) The function module as claimed in claim 15, wherein the first circuit board further includes a third surface, opposite to the first surface, with a first device located thereon.
18. (Original) The function module as claimed in claim 15, wherein the second circuit board further includes a fourth surface, opposite to the second surface, with a second device located thereon.

19. (Original) The function module as claimed in claim 15, wherein the first heat conduction layer comprises a copper layer.

20. (Original) The function module as claimed in claim 15, wherein the second heat conduction layer comprises a copper layer.

21. (Original) The function module as claimed in claim 15, further comprising a flat cable connecting the first circuit board and the second circuit board, providing communicability therebetween.

22. (Original) The function module as claimed in claim 15, wherein the first circuit board includes a first connector, the second circuit board includes a second connector corresponding to the first connector, and the first circuit board and the second circuit board communicate with each other by the respective connectors.

23. (Original) The function module as claimed in claim 22, wherein the first connector is located on the first surface, and the second connector is located on the second surface.

24. (Original) The function module as claimed in claim 15, further comprising a slot connector connecting the first circuit board and the second circuit board, providing communicability therebetween.

25. (Original) The function module as claimed in claim 15, wherein the plate-type heat dissipation device is a plate-type heat pipe, a copper plate, a plate-type copper block, a micro fin, a water-cooling device, or a vapor chamber.

26. (Original) The function module as claimed in claim 15, further comprising a heat dissipation fin, connected to the plate-type heat dissipation device, for dissipating heat therefrom.

27. (Original) The function module as claimed in claim 26, further comprising a fan, connected to the heat dissipation fin, for dissipating heat therefrom.

28. (Original) The function module as claimed in claim 15, further comprising:
a first adhesion layer, disposed between the plate-type heat dissipation device and the first heat conduction layer, attaching the plate-type heat dissipation device to the first circuit board; and
a second adhesion layer, disposed between the plate-type heat dissipation device and the second heat conduction layer, attaching the plate-type heat dissipation device to the second circuit board.

29. (Original) The function module as claimed in claim 28, wherein both the first adhesion layer and the second adhesion layer comprise one selected from the group consisting of brazing solder, tin solder, thermal interface material, or grease and the combination thereof respectively.

In the Drawings

FIG. 5b is amended to include a fan 155.

Attachments:

Annotated Drawing Sheet

Replacement Drawing Sheet